

Spectra7 and Teledyne LeCroy to Demonstrate Robust Performance Testing of 800Gbps Active Copper Interconnects at DesignCon 2024

Demo to Highlight Spectra7's GC1122 and Teledyne LeCroy's Xena Z800 Freya 800GE Test System

SAN JOSE, Calif., Jan. 31, 2024 /CNW/ -- (TSXV:SEV) (OTCQB:SPVNF) Spectra7 Microsystems Inc. ("Spectra7" or the "Company"), a leading provider of high-performance analog semiconductor products for broadband connectivity markets, and Teledyne LeCroy, a leading provider of electronic design, test and software solutions, announced they will demonstrate their latest 800Gbps product offerings at this year's annual DesignCon Conference Exhibition in Santa Clara, California from Jan 31-Feb 1, 2024. The companies plan to demonstrate robust performance and testing of 800Gbps Active Copper Cable (ACC) products for hyperscale data center applications.

The demo will highlight Spectra7's ACCs successfully interoperating with the Teledyne LeCroy's Xena Z800 800GE QSFP-DD800 Test System at 800Gbps speeds. Link training will show a very robust low pre-FEC bit error rate (BER) which demonstrates a wide margin over standard required BER.

DesignCon is the premier high-speed interconnect and system design conference attended by engineers from around the world. The Spectra7 will be on exhibit in booth #1344.

"We are excited to be working with Spectra7 on showcasing Active Copper Cable options for the rapidly expanding data center interconnect market," said Claus Hoyer, VP Technology and Architecture at XENA/Teledyne LeCroy. "Spectra7 has created a compelling solution to address the dramatically increasing power and cost of data center interconnects."

"Teledyne LeCroy is a global leader in the test and measurement solutions market," said Spectra7 CEO Raouf Halim. "The collaboration with them and demonstration of our GaugeChanger™ technology is a significant milestone in the coming volume deployment of our data center product line."

Spectra7's analog based GaugeChanger™ GC1122 chips are used in ACCs and offer significant cost, size, and energy consumption value versus competing Active Electrical Cables (AECs) and Active Optical Cables (AOCs) that use Digital Signal Processing (DSP) technologies.

ABOUT Teledyne LeCroy

Teledyne LeCroy is a leading manufacturer of advanced oscilloscopes, protocol analyzers, and other test instruments that verify performance, validate compliance, and debug complex electronic systems quickly and thoroughly. Since its founding in 1964, the Company has focused on incorporating powerful tools into innovative products that enhance "Time-to-Insight". Faster time to insight enables users to rapidly find and fix defects in complex electronic systems, dramatically improving time-to-market for a wide variety of applications and end markets. Teledyne LeCroy is based in Chestnut Ridge, New York. For more information, visit Teledyne LeCroy's website at teledynelecroy.com.

ABOUT SPECTRA7 MICROSYSTEMS INC.

Spectra7 Microsystems Inc. is a high-performance analog semiconductor company delivering unprecedented bandwidth, speed and resolution to enable disruptive industrial design for leading electronics manufacturers in virtual reality, augmented reality, mixed reality, data centers and other connectivity markets. Spectra7 is based in San Jose, California with a design center in Cork, Ireland and a technical support location in Dongguan, China. For more information, please visit www.spectra7.com.

Neither the TSX Venture Exchange nor its regulation services provider (as that term is defined in the policies of the TSX Venture Exchange) accepts responsibility for the adequacy or accuracy of this release.

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Certain statements contained in this press release constitute "forward-looking statements". All statements other than statements of historical fact contained in this press release, including, without limitation, the Company's strategy, plans, objectives, goals and targets, and any statements preceded by, followed by or that include the words "believe", "expect", "aim", "intend", "plan", "continue", "will", "may", "would", "anticipate", "estimate", "forecast", "predict", "project", "seek", "should" or similar expressions or the negative thereof, are forward-looking statements. These statements are not historical facts but instead represent only the Company's expectations, estimates and projections regarding future events. These statements are not guarantees of future performance and involve assumptions, risks and uncertainties that are difficult to predict. Therefore, actual results may differ materially from what is expressed, implied or forecasted in such forward-looking statements. Additional factors that could cause actual results, performance or achievements to differ materially include, but are not limited to, the risk factors discussed in the Company's management's discussion and analysis for the year ended December 31, 2022. Management provides forward-looking statements because it believes they provide useful information to investors when considering their investment objectives and cautions investors not to place undue reliance on forward-looking information. Consequently, all of the forward-looking statements made in this press release are qualified by these cautionary statements and other cautionary statements or factors contained herein, and there can be no assurance that the actual results or developments will be realized or, even if substantially realized, that they will have the expected consequences to, or effects on, the Company. These forward-looking statements are made as of the date of this press release and the Company assumes no obligation to update or revise them to reflect subsequent information, events or circumstances or otherwise, except as required by law.

For more information, please contact:

Matt Kreps
Darrow Associates
214-597-8200
ir@spectra7.com

Spectra7 Microsystems Inc.
Dave Mier
Interim Chief Financial Officer
925-858-7011
ir@spectra7.com

Spectra7 Microsystems Inc.
John Mitchell
Public Relations
650-269-3043
pr@spectra7.com

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